

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Seiji FUNABA</td> <td>06/17/2013</td> </tr> <tr> <td>Yasuo NOTO</td> <td>06/19/2013</td> </tr> <tr> <td>Masashige TSUJI</td> <td>06/17/2013</td> </tr> <tr> <td>Keiji KUNII</td> <td>06/17/2013</td> </tr> <tr> <td>Koichi YAHATA</td> <td>06/17/2013</td> </tr> <tr> <td>Shinichiro HIDA</td> <td>06/17/2013</td> </tr> </tbody> </table>		Name	Execution Date	Seiji FUNABA	06/17/2013	Yasuo NOTO	06/19/2013	Masashige TSUJI	06/17/2013	Keiji KUNII	06/17/2013	Koichi YAHATA	06/17/2013	Shinichiro HIDA	06/17/2013
Name	Execution Date														
Seiji FUNABA	06/17/2013														
Yasuo NOTO	06/19/2013														
Masashige TSUJI	06/17/2013														
Keiji KUNII	06/17/2013														
Koichi YAHATA	06/17/2013														
Shinichiro HIDA	06/17/2013														
RECEIVING PARTY DATA															
Name:	Hitachi Automotive Systems, Ltd.														
Street Address:	2520, Takaba														
City:	Hitachinaka-shi, Ibaraki														
State/Country:	JAPAN														
PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13981476</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13981476										
Property Type	Number														
Application Number:	13981476														
CORRESPONDENCE DATA															
Fax Number:	2026288844														
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>															
Phone:	2026242500														
Email:	abanerjee@crowell.com														
Correspondent Name:	Crowell & Moring LLP														
Address Line 1:	P.O. Box 14300														
Address Line 4:	Washington, DISTRICT OF COLUMBIA 20044-4300														
NAME OF SUBMITTER:	Michael H. Jacobs														
Signature:	/Michael H. Jacobs/														
Date:	09/11/2013														
Total Attachments: 1 source=65722US_Executed_Assignment#page1.tif															

OP \$40.00 13981476

PATENT

ASSIGNMENT
(讓渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi Automotive Systems, Ltd., a corporation organized under the laws of Japan, located at 2520, Takaba, Hitachinaka-shi, Ibaraki Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Automotive Systems, Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

POWER INVERTER

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi Automotive Systems, Ltd., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Automotive Systems, Ltd.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (發明者フルネームサイン)	Date Signed (署名日)
1) <u>Seiji Funaba</u> Seiji FUNABA	<u>6/17/2013</u>
2) <u>Yasuo Noto</u> Yasuo NOTO	<u>6/19/2013</u>
3) <u>Masashige Tsuji</u> Masashige TSUJI	<u>6/17/2013</u>
4) <u>Keiji Kunii</u> Keiji KUNII	<u>6/17/2013</u>
5) <u>Koichi Yahata</u> Koichi YAHATA	<u>6/17/2013</u>
6) <u>Shinichiro Hida</u> Shinichiro HIDA	<u>6/17/2013</u>
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____

PATENT